



FORM PTO-1449 (SUBSTITUTE)

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEINFORMATION DISCLOSURE  
STATEMENT BY APPLICANT  
(37 CFR 1.98(b))Attorney Docket No.:  
GR 98 P 4137 PApplic. No.  
09/761,594Applicant  
Hans-Jürgen Hacke et al.Filing Date  
January 16, 2001

Group Art Unit

## U.S. PATENT DOCUMENTS

EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
JTH	A	4,922,321	05/01/90	Arai et al.	—	—	—
JTH	B	5,074,947	12/24/91	Estes et al.	—	—	—
JTH	C	5,477,087	12/19/95	Kawakita et al.	—	—	—
	D						
	E						
	F						
	G						
	H						
	I						

## FOREIGN PATENT DOCUMENT

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES   NO
JTH	J	0 734 059 A2	09/25/96	European	—	—	X
JTH	K	05 062 981	03/12/93	Japan	—	—	X
JTH	L	06 232 134	08/19/94	Japan	—	—	X
	M						
	N						

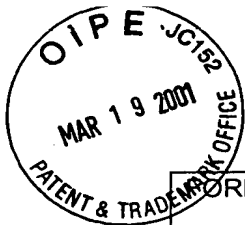
## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

JTH	O	International Publication WO 96/22620 (Pedersen et al.), dated July 25, 1996
JTH	P	Shinji Baba et al.: "Molded Chip Scale package for High Pin Count", 1996 Electronic Components and Technology Conference, pp. 1251-1257, XP-000684987

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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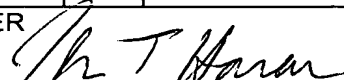
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

	O	"Solder Plated Resin Ball", IBM Technical Disclosure Bulletin, pp. 463-464
	P	

EXAMINER 	DATE CONSIDERED 4/17/02
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